

ABSTRACT OF THE DISCLOSURE

A baking system includes a heat pipe including a top surface for receiving a wafer to be baked, the heat pipe to be filled with a predetermined amount of working fluid and having wicks formed on sides and a ceiling thereof for supplying the working fluid, a heater for heating the top surface by heating the working fluid, a subsidiary cooling system, which contains a liquid coolant that is to be exchanged with the working fluid from the heat pipe through circulation, a connection pipe for providing fluid communication between the heat pipe and the subsidiary cooling system to circulate the working fluid and the liquid coolant, and a control unit, which is installed in the connection pipe, for controlling a flow of the working fluid and the liquid coolant through the connection pipe.